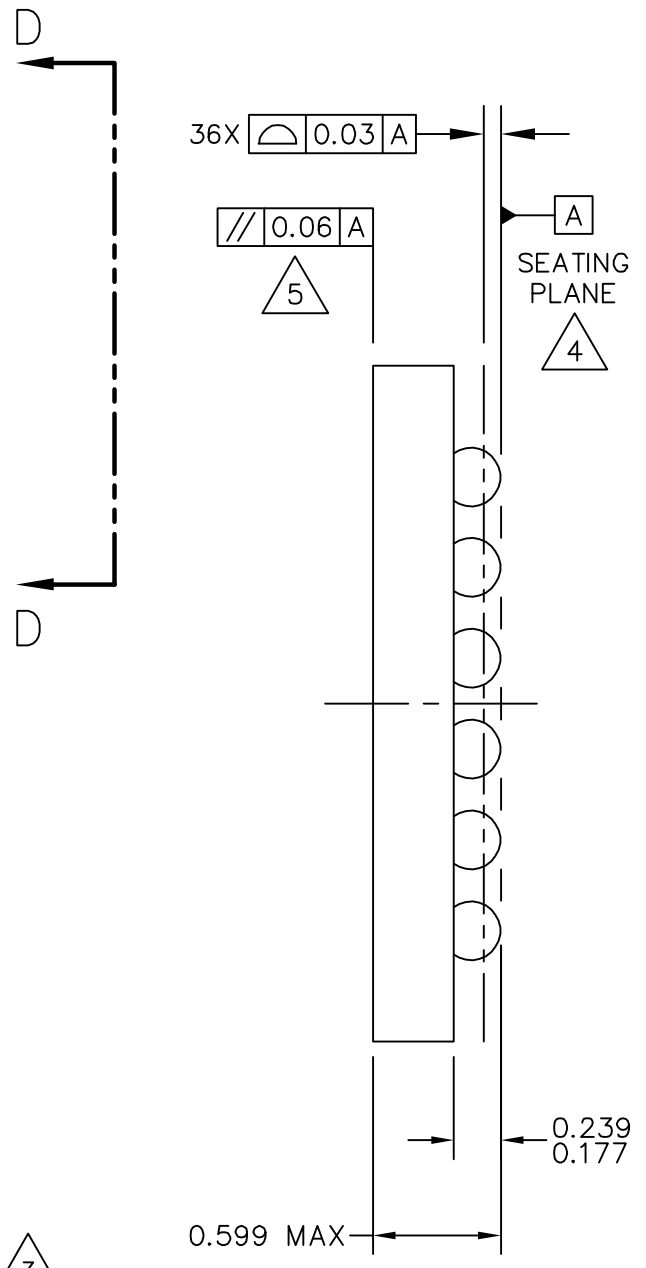
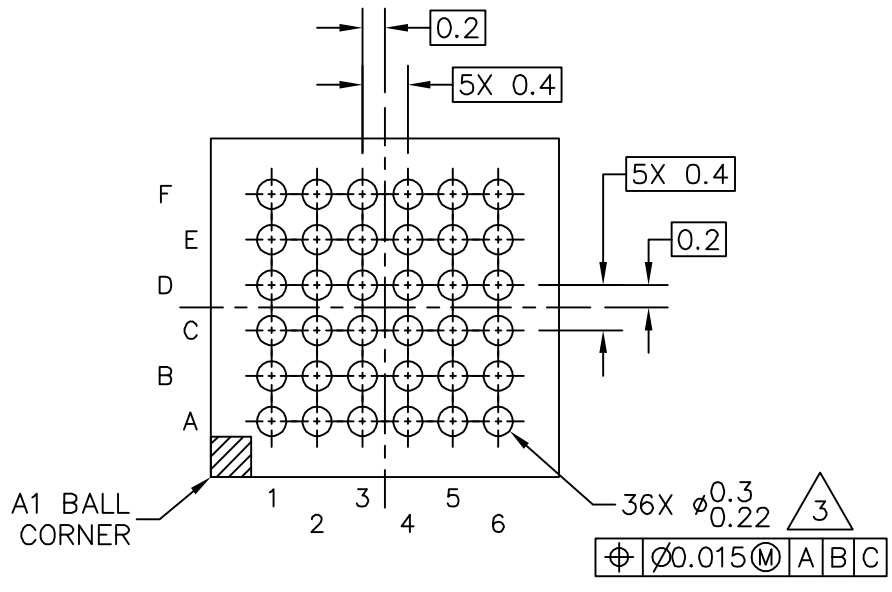


TOP VIEW



VIEW D-D



BOTTOM VIEW

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: WLCSP, 3.07 X 2.98 X 0.564 PKG, 0.4 MM PITCH, 36 I/O	DOCUMENT NO: 98ASA00789D	REV: A
	STANDARD: NON-JEDEC	
	SOT1780-1	13 JAN 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: WLCSP, 3.07 X 2.98 X 0.564 PKG, 0.4 MM PITCH, 36 I/O		DOCUMENT NO: 98ASA00789D	REV: A
		STANDARD: NON-JEDEC	
		SOT1780-1	13 JAN 2016